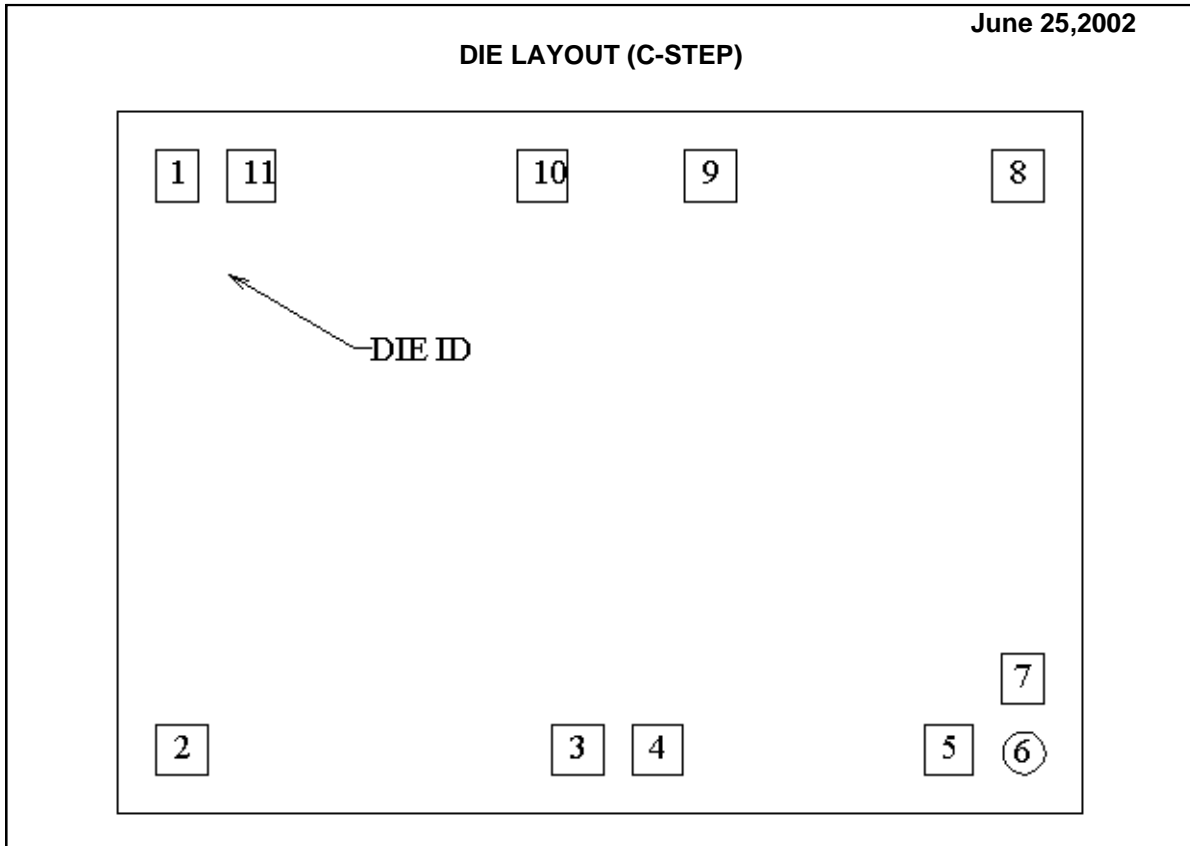


**LM119 MDS MCD1410A
HIGH SPEED DUAL COMPARATOR**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	119C	Bond Pad Opening Size (min)	91µm x 109µm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	GOLD BACK
Die Size (Drawn)	2057µm x 1499µm 81mils x 59mils	Back Side Connection	V-
Thickness	330µm Nominal		
Min Pitch	157µm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron. V- connected to die backside.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
Output 1	1	-902	613	91	x	109
GND 1	2	-893	-613	109	x	109
+Input 1	3	-47	-613	109	x	109
-Input 1	4	123	-613	109	x	109
V-	5	744	-613	102	x	109
NC	6	902	-622	91	x	91
Output 2	7	902	-461	91	x	109
Gnd 2	8	893	613	109	x	109
+Input 2	9	237	613	109	x	109
-Input 2	10	-123	613	109	x	109
V+	11	-744	613	102	x	109

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